BUT11AI

GENERAL DESCRIPTION

Enhanced performance, high speed switching npn transistor in TO220AB envelope specially suited for high frequency electronic lighting ballast applications and converters, inverters, switching regulators, motor control systems etc.

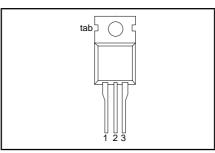
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_{CESM}	Collector-emitter voltage peak value	$V_{BF} = 0 \text{ V}$	-	1000	V
V _{CEO}	Collector-emitter voltage (open base)		-	450	V
I _C	Collector current (DC)		-	5	Α
1 17	Collector current peak value		-	10	Α
I _{CM} P _{tot} V _{CEsat}	Total power dissipation	$T_{mb} \le 25 ^{\circ}\text{C}$ $I_{C} = 2.5 \text{A}; I_{B} = 0.33 \text{A}$	-	100	W
V _{CEsat}	Collector-emitter saturation voltage	$I_{\rm C} = 2.5 \text{ A}; I_{\rm B} = 0.33 \text{ A}$	-	1.5	V
I _{Csat}	Collector Saturation current		2.5		Α
t _f	Inductive fall time	$I_{Con} = 2.5 \text{ A}; I_{Bon} = 0.5 \text{ A}$	0.08	0.15	μs

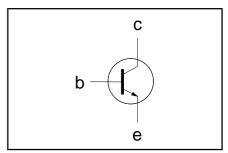
PINNING - TO220AB

PIN	DESCRIPTION	
1	pase	
2	collector	
3	emitter	
tab	collector	

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CESM}	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$		1000	V
V _{CEO}	Collector-emitter voltage (open base)		-	450	V
I _C	Collector current (DC)		-	5	Α
I _{CM}	Collector current peak value		-	10	Α
I _B	Base current (DC)		-	2	Α
I _{BM}	Base current peak value		-	4	Α
P _{tot}	Total power dissipation	$T_{mb} \leq 25 ^{\circ}C$	-	100	W
T _{stg}	Storage temperature		-65	150	°C
T_{j}	Junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
R _{th j-mb}	Junction to mounting base		-	1.25	K/W
R _{th j-a}	Junction to ambient	in free air	-	60	K/W

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STATIC CHARACTERISTICS

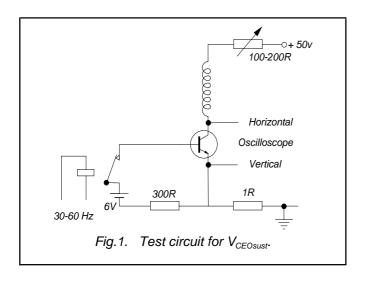
 $T_{mb} = 25$ °C unless otherwise specified

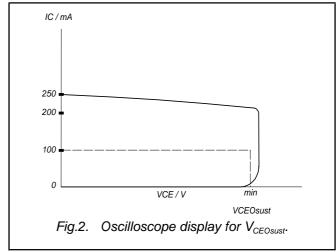
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CES}	Collector cut-off current ¹	$V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}, V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}; T_{:} = 125 \text{ °C}$	-	-	1.0 2.0	mA mA
V_{CEOsust}	Emitter cut-off current Collector-emitter sustaining voltage	$V_{EB} = 9.0 \text{ V}; I_{C} = 0 \text{ A}$ $I_{B} = 0 \text{ A}; I_{C} = 100 \text{ mA};$ $I_{C} = 25 \text{ mH}$	- 450	-	10.0	mA V
V _{CEsat} V _{BEsat} h _{FE} h _{FE} h _{FEsat}	Collector-emitter saturation voltage Base-emitter saturation voltage DC current gain	$I_{C} = 2.5 \text{ A}; I_{B} = 0.33 \text{ A}$ $I_{C} = 2.5 \text{ A}; I_{B} = 0.33 \text{ A}$ $I_{C} = 5 \text{ mA}; V_{CE} = 5 \text{ V}$ $I_{C} = 0.5 \text{ A}; V_{CE} = 5 \text{ V}$ $I_{C} = 2.5 \text{ A}; V_{CE} = 5 \text{ V}$	- 10 14 9	- 20 22 13	1.5 1.3 35 35 17	V

DYNAMIC CHARACTERISTICS

 $T_{mb} = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
	Switching times resistive load	$I_{Con} = 2.5 \text{ A}; I_{Bon} = 0.5 \text{ A}; -I_{Boff} = 0.5 \text{ A}$			
t _{on}	Turn-on time		0.6	1.0	μs
t _s	Turn-off storage time Turn-off fall time		3.4 0.6	4.0 0.8	μs μs
t _s	Switching times inductive load Turn-off storage time Turn-off fall time	$\begin{split} I_{Con} &= 2.5 \text{ A}; \ I_{Bon} = 0.5 \text{ A}; \ L_{B} = 1 \mu\text{H}; \\ -V_{BB} &= 5 \text{ V} \end{split}$ $I_{Con} &= 2.5 \text{ A}; \ I_{Bon} = 0.5 \text{ A}; \ L_{B} = 1 \mu\text{H}; \\ -V_{BB} &= 5 \text{ V}; \ T_{i} = 100 \text{ °C} \end{split}$	1.1 80	1.4 150	μs ns
t _s	Turn-off storage time Turn-off fall time	VBB - 3 V, 1 _j - 100 O	1.2 140	1.5 300	μs ns





¹ Measured with half sine-wave voltage (curve tracer).

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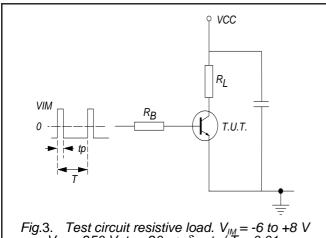


Fig.3. Test circuit resistive load. V_{IM} = -6 to +8 V V_{CC} = 250 V; t_p = 20 μ s; δ = t_p / T = 0.01. R_B and R_L calculated from I_{Con} and I_{Bon} requirements.

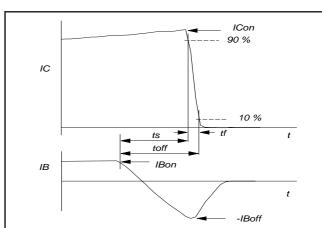


Fig.6. Switching times waveforms with inductive load.

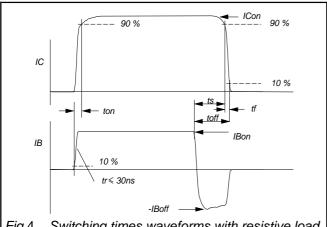


Fig.4. Switching times waveforms with resistive load.

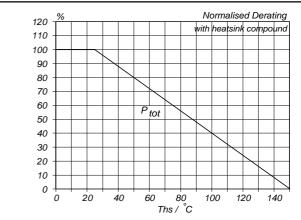
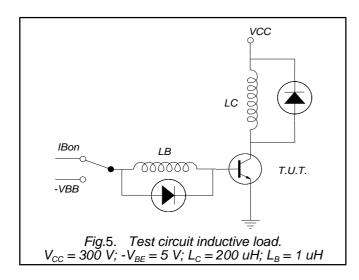
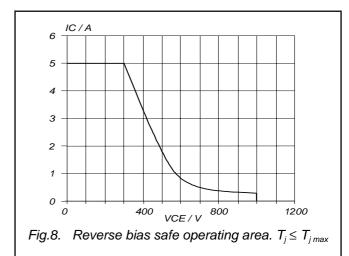
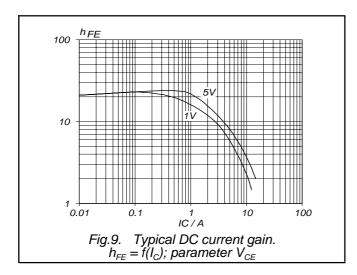


Fig.7. Normalised power derating and second breakdown curves.





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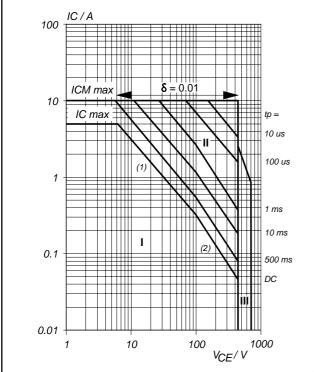


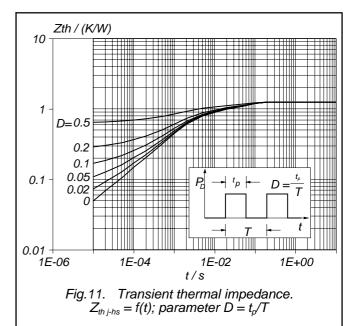
Fig. 10. Forward bias safe operating area. $T_{hs} \le 25$ °C

- (1) (2)

- P_{tot} max and P_{tot} peak max lines. Second breakdown limits. Region of permissible DC operation. Extension for repetitive pulse operation. II
- III
- NB:
- Extension during turn-on in single transistor converters provided that $R_{BE} \le 100 \,\Omega$ and $t_p \le 0.6 \,\mu s$.

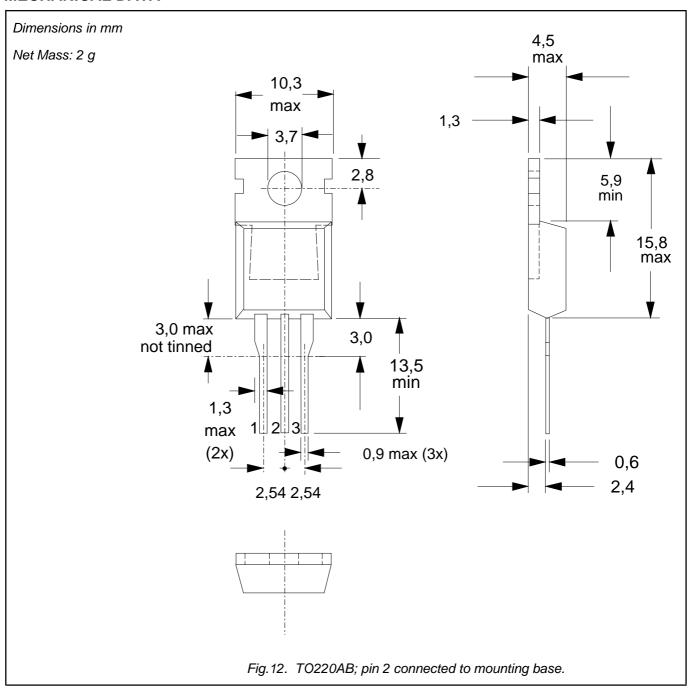
 Mounted with heatsink compound and 30 ± 5 newton force on the centre of the

envelope.



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MECHANICAL DATA



- Notes
 1. Refer to mounting instructions for TO220 envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

Silicon Diffused Power Transistor

BUT11AI

DEFINITIONS

DATA SHEET STATUS				
DATA SHEET STATUS ²	PRODUCT STATUS ³	DEFINITIONS		
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice		
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product		
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A		

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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April 2002 6 Rev 2.000

² Please consult the most recently issued datasheet before initiating or completing a design.

³ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.